

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4262803

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CHUNG-YEH LEE	12/30/2016
CHIH-PING LIN	01/18/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	VANGUARD INTERNATIONAL SEMICONDUCTOR CORPORATION
<b>Street Address:</b>	123, PARK AVE-3RD, SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	30077
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15425673
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)205-8050
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<b>ATTORNEY DOCKET NUMBER:</b>	0941-3521PUS1
<b>NAME OF SUBMITTER:</b>	TUYEN LY
<b>SIGNATURE:</b>	/tuyen ly/
<b>DATE SIGNED:</b>	02/07/2017
<b>Total Attachments: 2</b>	
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source=2017-02-06-ASSIGNMENT-0941-3521PUS1#page2.tif	

**ASSIGNMENT**

WHEREAS, Chung-Yeh LEE and Chih-Ping LIN  
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements  
as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR FORMING SEMICONDUCTOR DEVICE STRUCTURE

Filed: 02/06/2017 Serial No. 15/425,673

Executed on: 12/30/2016; 01/18/2017

WHEREAS, Vanguard International Semiconductor Corporation  
of 123, Park Ave-3rd, Science - Based Industrial Park, Hsinchu,  
Taiwan 30077, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring  
ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent  
which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for  
good and valuable consideration, receipt of which is hereby acknowledged by Assignor,  
Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign  
and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their  
rights, title and interest in and to the said invention and application and all future  
improvements thereon, and in and to any Letters Patent which may hereafter be granted on the  
same in the United States, the said interest to be held and enjoyed by said Assignee as fully  
and exclusively as it would have been held and enjoyed by said Assignor had this Assignment  
and transfer not been made, to the full end and term of any Letters Patent which may be  
granted thereon, or of any division, renewal, continuation in whole or in part, substitution,  
conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said  
Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said  
application and/or applications, execute, verify, acknowledge and deliver all such further  
papers, including applications for Letters Patent and for the reissue thereof, and instruments  
of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may  
request, to obtain or maintain Letters Patent for said invention and improvement, and to vest  
title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the  
date(s) indicated.

*Chung Yeh Lee*  
Chung-Yeh LEE

2016, 12, 30  
Date

\_\_\_\_\_  
Chih-Ping LIN

\_\_\_\_\_  
Date

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and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their  
rights, title and interest in and to the said invention and application and all future  
improvements thereon, and in and to any Letters Patent which may hereafter be granted on the  
same in the United States, the said interest to be held and enjoyed by said Assignee as fully  
and exclusively as it would have been held and enjoyed by said Assignor had this Assignment  
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request, to obtain or maintain Letters Patent for said invention and improvement, and to vest  
title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/hcr/their name(s) on the  
date(s) indicated.

\_\_\_\_\_  
Chung-Yeh LEE

\_\_\_\_\_  
Date

Chih-Ping LIN  
\_\_\_\_\_  
Chih-Ping LIN

01/18/2017  
\_\_\_\_\_  
Date